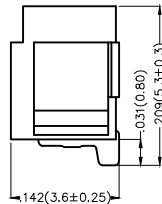
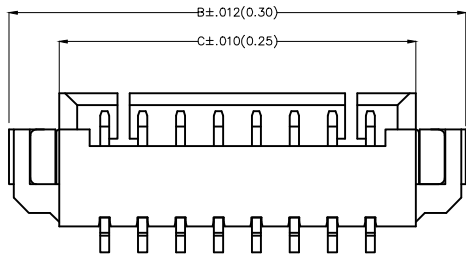
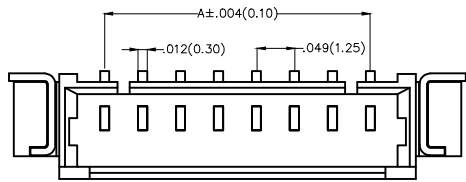
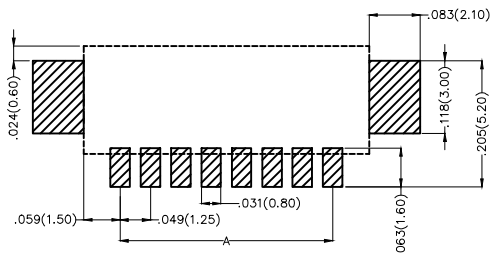


REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD



Electrical

Current Rating: 1.0A AC(rms)/DC
Voltage Rating: 125V AC(rms)/DC
Contact Resistance: 20 mΩ Max
Insulation Resistance: 100 MΩ MIN
Withstanding Voltage: 250V AC r.m.s
Temperature Range—Operating: -25°C ~ +85°C
Material and Plating
Housing: PA9T(UL 94V-0)
Contact Pin: Brass/ Tin plated
Solder Tab: Copper alloy/ Tin plated



Recommended P.C.Board Layout

Ordering Information



FWF 125 04 — S XX B X 4 W5 M
1 2 3 4 5 6 7 8 9 10

1	Category FWF—Wafer	2	Series Number 125—Pitch1.25mm	3	Distinction No. 04	4	Row Option S—Single Row	5	Circuits XX	6	Entry Angle B—90° Angle
7	Plating 2—Tin Plated	8	Material—Resin 4—PA9T	9	Color—Resin W5—Natural	10	Packaging M—Reel				

 THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 8/JUL/13	PART NO. FWF12504—SXXBX4W5M	ITEM NO. FWF12504	 Leader Of Industry	
	DESIGN UNITS Inch (metric)	X.±.012(0.30) X.X±.008(0.20) X.XX±.006(0.15) X.XXX±.004(0.10)	X.±5° .X±2° .XX±1° .XXX±0.5°	CHECKED BY JACOB	DATE 8/JUL/13	TITLE Wire to Board (Wafer) Pitch 1.25mm 90° Angle (SMT)		REV 1
SCALE 5:1	SIZE A4	DRAWN BY CHERRY		DATE 8/JUL/13	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD

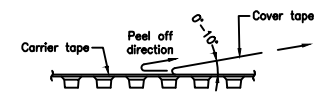
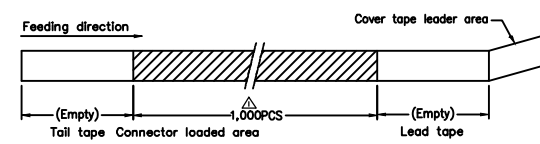
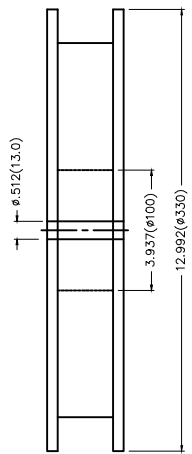
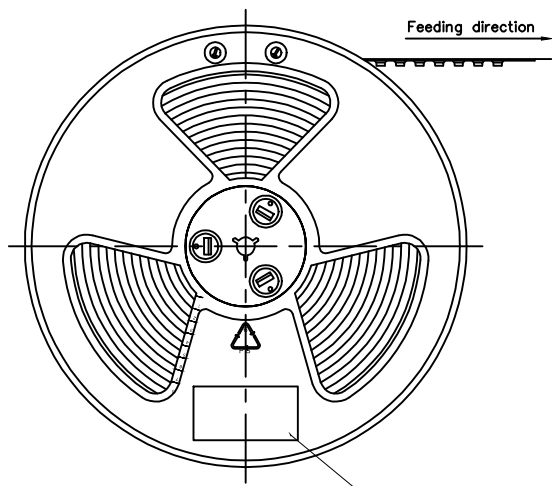
Circuits (n)	Part No.	Dimensions(in/mm)		
		A	B	C
2	FWF12504-S02B24W5M	.049(1.25)	.297(7.55)	.167(4.25)
3	FWF12504-S03B24W5M	.098(2.50)	.346(8.80)	.217(5.50)
4	FWF12504-S04B24W5M	.147(3.75)	.396(10.05)	.266(6.75)
5	FWF12504-S05B24W5M	.197(5.00)	.445(11.30)	.315(8.00)
6	FWF12504-S06B24W5M	.246(6.25)	.494(12.55)	.364(9.25)
7	FWF12504-S07B24W5M	.295(7.50)	.543(13.80)	.413(10.50)
8	FWF12504-S08B24W5M	.344(8.75)	.593(15.05)	.463(11.75)
9	FWF12504-S09B24W5M	.394(10.00)	.642(16.30)	.512(13.00)
10	FWF12504-S10B24W5M	.443(11.25)	.691(17.55)	.561(14.25)
11	FWF12504-S11B24W5M	.492(12.50)	.740(18.80)	.610(15.50)
12	FWF12504-S12B24W5M	.541(13.75)	.789(20.05)	.659(16.75)
13	FWF12504-S13B24W5M	.591(15.00)	.839(21.30)	.709(18.00)
14	FWF12504-S14B24W5M	.640(16.25)	.888(22.55)	.758(19.25)
15	FWF12504-S15B24W5M	.689(17.50)	.937(23.80)	.807(20.50)

 THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 8/JUL/13	PART NO. FWF12504-SXXBX4W5M	ITEM NO. FWF12504	 Leader Of Industry	
	X.±.012(0.30)	X.±5'	CHECKED BY JACOB	DATE 8/JUL/13	TITLE Wire to Board (Wafer) Pitch 1.25mm 90° Angle (SMT)			REV 1
	DESIGN UNITS Inch (metric)	X.XX±.008(0.20)	.X'±2"	DRAWN BY CHERRY	DATE 8/JUL/13	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
SCALE 5:1	SIZE A4	X.XXX±.004(0.10)	.XXX'±0.5'					

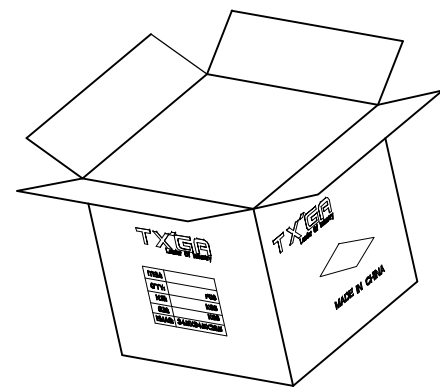
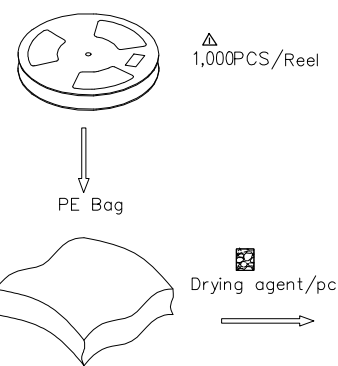
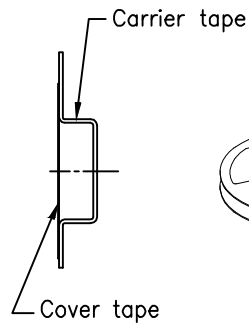
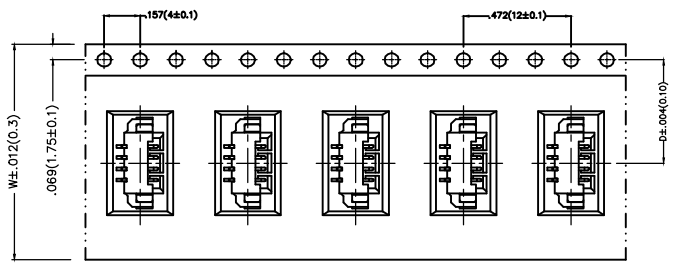
REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD
1	△	MPQ 1500PCS/Reel Change to 1000Pcs/Reel	20150811	CHERRY	JACOB

Note:

- 10 sprocket hole cumulative tolerance ± 0.2
- Carrier camber is within 1.0mm in 100mm
- Material: White Conductive polystyrene Alloy 100% recyclable
- All dimensions meet EIA-481-3 requirements
- Component load per 13" reel: 1,000 pcs



Circuits (n)	Dimensions(in/mm)		Circuits (n)	Dimensions(in/mm)	
	D	W		D	W
2	.295(7.50)	.630(16.00)	10	.559(14.20)	1.260(32.00)
3	.295(7.50)	.630(16.00)	11	.559(14.20)	1.260(32.00)
4	.453(11.50)	.945(24.00)	12	.559(14.20)	1.260(32.00)
5	.453(11.50)	.945(24.00)	13	.795(20.20)	1.732(44.00)
6	.453(11.50)	.945(24.00)	14	.795(20.20)	1.732(44.00)
7	.559(14.20)	1.260(32.00)	15	.795(20.20)	1.732(44.00)
8	.559(14.20)	1.260(32.00)			
9	.559(14.20)	1.260(32.00)			



 THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY	DATE	PART NO.	ITEM NO.	 Leader Of Industry
	X. \pm .012(0.30)	X.' \pm 5'	FRANK	8/JUL/13	FWF12504-SXXBX4W5M	FWF12504	
DESIGN UNITS Inch (metric)	X.XX \pm .008(0.20)	X' \pm 2'	CHECKED BY	DATE	TITLE		REV 1 SHEET NO. 3/3
SCALE	X.XX \pm .006(0.15)	.XX' \pm 1'	JACOB	8/JUL/13	Wire to Board (Wafer) Pitch 1.25mm 90° Angle (SMT)		
SIZE	X.XXX \pm .004(0.10)	.XXX' \pm 0.5'	DRAWN BY	DATE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
5:1	A4		CHERRY	8/JUL/13			